Retriggerable Monostable Multivibrators

These dc triggered multivibrators feature pulse width control by three methods. The basic pulse width is programmed by selection of external resistance and capacitance values. The LS122 has an internal timing resistor that allows the circuits to be used with only an external capacitor. Once triggered, the basic pulse width may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear.

- Overriding Clear Terminates Output Pulse
- Compensated for V_{CC} and Temperature Variations
- DC Triggered from Active-High or Active-Low Gated Logic Inputs
- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- Internal Timing Resistors on LS122

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
I _{OH}	Output Current – High			-0.4	mA
I _{OL}	Output Current – Low			8.0	mA
R _{ext}	External Timing Resistance	5.0		260	kΩ
C _{ext}	External Capacitance	No Restriction			
R _{ext} /C _{ext}	Wiring Capacitance at R _{ext} /C _{ext} Terminal			50	pF



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LOW POWER SCHOTTKY





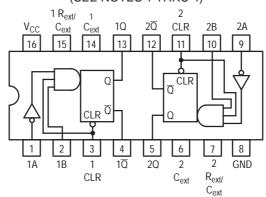




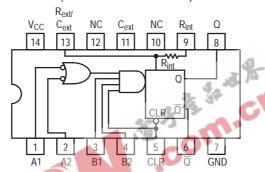
ORDERING INFORMATION

Device	Package	Shipping
SN74LS122N	14 Pin DIP	2000 Units/Box
SN74LS122D	14 Pin	2500/Tape & Reel
SN74LS123N	16 Pin DIP	2000 Units/Box
SN74LS123D	16 Pin	2500/Tape & Reel

SN74LS123 (TOP VIEW) (SEE NOTES 1 THRU 4)



SN74LS122 (TOP VIEW) (SEE NOTES 1 THRU 4)



NC - NO INTERNAL CONNECTION.

- 1. An external timing capacitor may be connected between C_{ext} and R_{ext}/C_{ext} (positive).
- 2. To use the internal timing resistor of the LS122, connect R_{int} to V_{CC} .

 3. For improved pulse width accuracy connect an external resistor between R_{ext}/C_{ext} and V_{CC} with R_{int} open-circuited.
- 4. To obtain variable pulse widths, connect an external variable resistance between R_{int}/C_{ext} and V_{CC}.

LS122 FUNCTIONAL TABLE

	INPUTS					
CLEAR	A1	A2	B1	B2	Q	Q
L	Х	Х	Х	Х	L	Н
X	Н	Н	Χ	X	L	Н
X	Х	Χ	L	Χ	L	Н
X	Х	Χ	X	L	L	Н
Н	L	Χ	\uparrow	Н	几	ъ
Н	L	Χ	Н	\uparrow	几	ъ
Н	Х	L	\uparrow	Н	$ \mathcal{A} $	ъ
Н	Х	L	Н	\uparrow	л	T
Н	Н	\downarrow	Н	Н		ъ
Н	\downarrow	\downarrow	Н	Н	1	ъ
Н	\downarrow	Н	Н	Н	л	ъ
1	L	X	Н	Н	几	ъ
1	Х	L	Н	Н	九	Ъ

LS123 FUNCTIONAL TABLE

INF	OUT	PUTS		
CLEAR	Α	В	Q	Q
L	Х	Х	L	Н
X	Н	X	L	Н
X	Х	L	L	Н
Н	L	\uparrow	Л	ъ
Н	\downarrow	Н	л	ъ
1	L	Н	Л	ъ

TYPICAL APPLICATION DATA

The output pulse t_W is a function of the external components, C_{ext} and R_{ext} or C_{ext} and R_{int} on the LS122. For values of $C_{ext} \ge 1000$ pF, the output pulse at $V_{CC} = 5.0$ V and $V_{RC} = 5.0$ V (see Figures 1, 2, and 3) is given by

$$t_W = K R_{ext} C_{ext}$$
 where K is nominally 0.45

If C_{ext} is on pF and R_{ext} is in $k\Omega$ then t_W is in nanoseconds. The C_{ext} terminal of the LS122 and LS123 is an internal connection to ground, however for the best system performance C_{ext} should be hard-wired to ground.

Care should be taken to keep R_{ext} and C_{ext} as close to the monostable as possible with a minimum amount of inductance between the R_{ext}/C_{ext} junction and the R_{ext}/C_{ext} pin. Good groundplane and adequate bypassing should be designed into the system for optimum performance to ensure that no false triggering occurs.

It should be noted that the C_{ext} pin is internally connected to ground on the LS122 and LS123, but not on the LS221. Therefore, if C_{ext} is hard-wired externally to ground, substitution of a LS221 onto a LS123 socket will cause the LS221 to become non-functional.

The switching diode is not needed for electrolytic capacitance application and should not be used on the LS122 and LS123.

To find the value of K for $C_{ext} \ge 1000$ pF, refer to Figure 4. Variations on V_{CC} or V_{RC} can cause the value of K to change, as can the temperature of the LS123, LS122.

Figures 5 and 6 show the behavior of the circuit shown in Figures 1 and 2 if separate power supplies are used for V_{CC} and V_{RC} . If V_{CC} is tied to V_{RC} , Figure 7 shows how K will vary with V_{CC} and temperature. Remember, the changes in R_{ext} and C_{ext} with temperature are not calculated and included in the graph.

As long as $C_{\text{ext}} \ge 1000 \text{ pF}$ and $5K \le R_{\text{ext}} \le 260K$, the change in K with respect to R_{ext} is negligible.

If $C_{ext} \le 1000$ pF the graph shown on Figure 8 can be used to determine the output pulse width. Figure 9 shows how K will change for $C_{ext} \le 1000$ pF if V_{CC} and V_{RC} are connected to the same power supply. The pulse width t_W in nanoseconds is approximated by

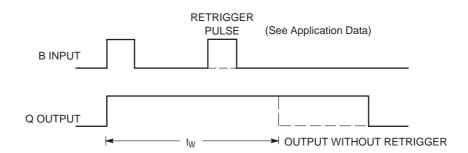
$$t_W = 6 + 0.05 C_{ext} (pF) + 0.45 R_{ext} (k\Omega) C_{ext} + 11.6 R_{ext}$$

In order to trim the output pulse width, it is necessary to include a variable resistor between V_{CC} and the R_{ext}/C_{ext} pin or between V_{CC} and the R_{ext} pin of the LS122. Figure 10, 11, and 12 show how this can be done. R_{ext} remote should be kept as close to the monostable as possible.

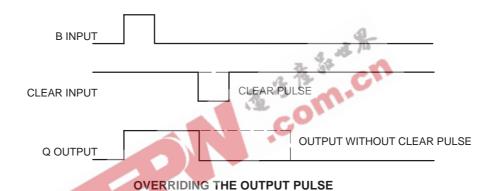
Retriggering of the part, as shown in Figure 3, must not occur before C_{ext} is discharged or the retrigger pulse will not have any effect. The discharge time of C_{ext} in nanoseconds is guaranteed to be less than 0.22 C_{ext} (pF) and is typically 0.05 C_{ext} (pF).

For the smallest possible deviation in output pulse widths from various devices, it is suggested that C_{ext} be kept $\geq 1000 \ pF$.

WAVEFORMS



EXTENDING PULSE WIDTH



DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

				Limits				
Symbol	Parameter		Min	Тур	Max	Unit	Test C	onditions
V _{IH}	Input HIGH Voltage		2.0			V	Guaranteed Inp All Inputs	ut HIGH Voltage for
V _{IL}	Input LOW Voltage				0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V _{IK}	Input Clamp Diode Voltage			-0.65	-1.5	V	V _{CC} = MIN, I _{IN} =	= –18 mA
V _{OH}	Output HIGH Voltage		2.7	3.5		V	$V_{CC} = MIN, I_{OH}$ or V_{IL} per Truth	= MAX, V _{IN} = V _{IH} Table
	Output I OW Valtage			0.25	0.4	V	I _{OL} = 4.0 mA	$V_{CC} = V_{CC} MIN,$
V _{OL}	Output LOW Voltage			0.35	0.5	V	I _{OL} = 8.0 mA	$V_{IN} = V_{IL}$ or V_{IH} per Truth Table
	land till Cit Compart				20	μΑ	V _{CC} = MAX, V _{IN}	_I = 2.7 V
Iн	Input HIGH Current				0.1	mA	$V_{CC} = MAX, V_{IN}$	_I = 7.0 V
I _{IL}	Input LOW Current				-0.4	mA	$V_{CC} = MAX, V_{IN} = 0.4 V$	
I _{OS}	Short Circuit Current (Note 1)	-20		-100	mA	V _{CC} = MAX	
laa	Dawas Sunah Cumant				11	m^4	\/aa = MAY	
Icc	Power Supply Current	LS123			20	m A	V _{CC} = MAX	

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second. **AC CHARACTERISTICS** $(T_A = 25^{\circ}C, V_{CC} = 5.0 \text{ V})$

			Limits	CO		
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t _{PLH}	Propagation Delay, A to Q		23	33	ns	
t _{PHL}	Propagation Delay, A to Q		32	45	115	C _{ext} = 0
t _{PLH}	Propagation Delay, B to Q		23	44		C _L = 15 pF
t _{PHL}	Propagation Delay, B to Q		34	56	ns	$R_{\text{ext}} = 5.0 \text{ k}\Omega$
t _{PLH}	Propagation Delay, Clear to Q		28	45		$R_L = 2.0 \text{ k}\Omega$
t _{PHL}	Propagation Delay, Clear to Q		20	27	ns	
t _{W min}	A or B to Q		116	200	ns	$C_{\text{ext}} = 1000 \text{ pF}, R_{\text{ext}} = 10 \text{ k}\Omega,$
t _W Q	A to B to Q	4.0	4.5	5.0	μs	$C_L = 15 \text{ pF}, R_L = 2.0 \text{ k}\Omega$

AC SETUP REQUIREMENTS ($T_A = 25$ °C, $V_{CC} = 5.0 \text{ V}$)

		Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
t _W	Pulse Width	40			ns	

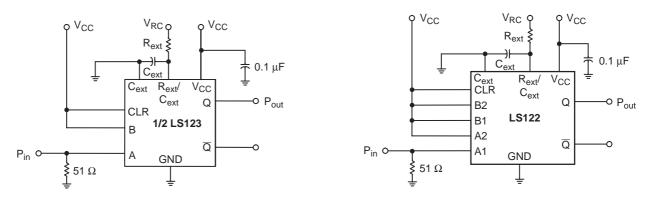


Figure 1.

Figure 2.

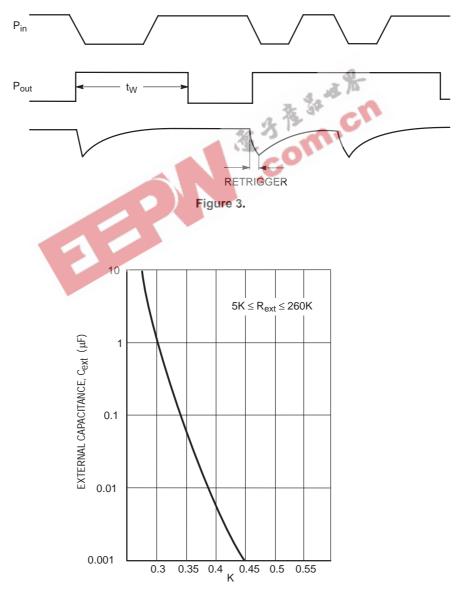
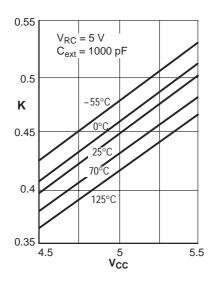
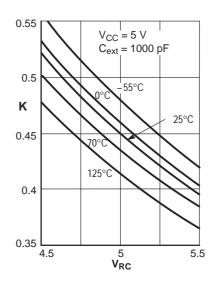


Figure 4.





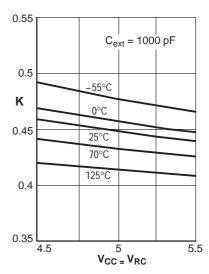


Figure 5. K versus $V_{\rm CC}$

Figure 6. K versus V_{RC}

Figure 7. K versus $\rm V_{CC}$ and $\rm V_{RC}$

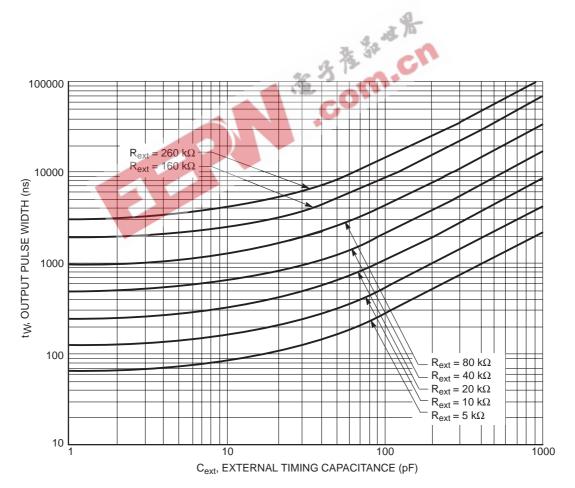


Figure 8.

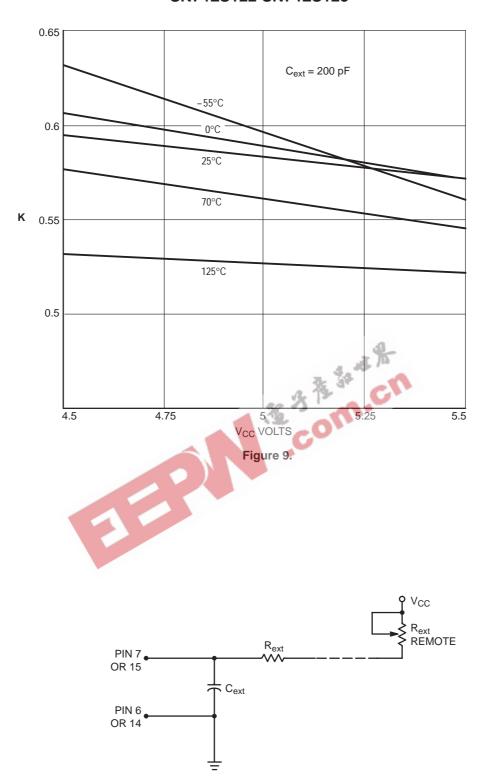


Figure 10. LS123 Remote Trimming Circuit

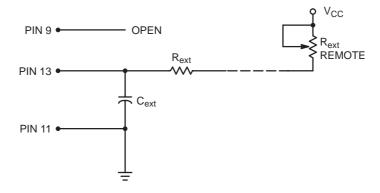


Figure 11. LS122 Remote Trimming Circuit Without R_{ext}

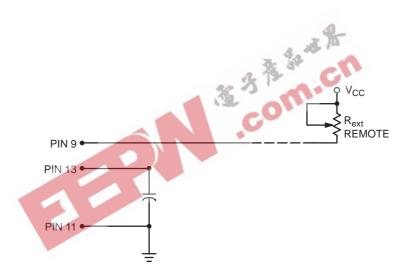
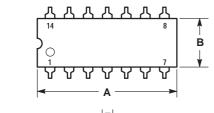


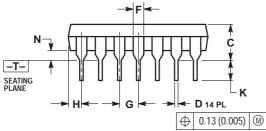
Figure 12. LS122 Remote Trimming Circuit with R_{int}

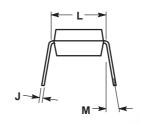
PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 646-06

ISSUE M







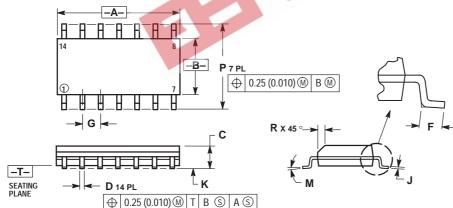
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- 7/14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN
- FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.715	0.770	18.16	18.80
В	0.240	0.260	6.10	6.60
С	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100	BSC	2.54 BSC	
Н	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M		10°		10°
N	0.015	0.039	0.38	1.01

D SUFFIX C SOIC PACK' SE 751A ISS' PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



NOTES:

- IOLES:
 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE
 MOLD PROTRUSION.

- MOLD PROTRUSION.

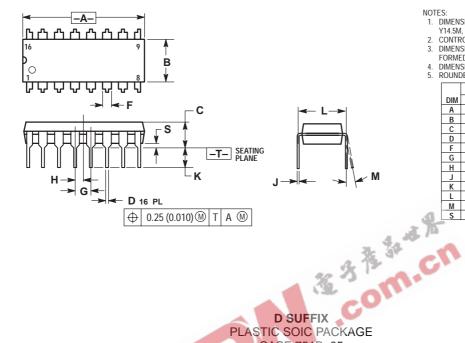
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0 °	7°	0 °	7°	
Р	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	

PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 648-08 ISSUE R

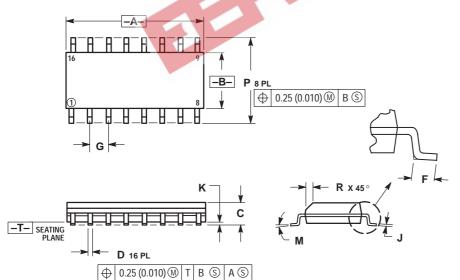


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEADS WHEN
 FORMED PARALLEL.
 DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
Κ	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0°	10 °	
S	0.020	0.040	0.51	1.01	

D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- 714.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MOLD FROTTO-SIGN TO SOCIETY PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INC	HES	
DIM	MIN			MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	



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